

Title (en)
Additive for plating bath

Title (de)
Zusatz für Plattierungsbad

Title (fr)
Additif pour bain de placage

Publication
EP 1555335 A2 20050720 (EN)

Application
EP 05250172 A 20050114

Priority
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Abstract (en)
A plating bath additive and a plating bath using the said additive are provided, which plating bath contains a hydroxyalkanesulfonic acid and which even when applied to an electronic part such as a semiconductor device does not give rise to a problem such as circuit-to-circuit insulation becoming defective. The plating bath additive contains a hydroxyalkanesulfonic acid as a main component and has an alkali metal content of less than 0.05 mass% relative to the hydroxyalkanesulfonic acid. The plating bath incorporates the said additive therein.

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C23C 18/16

IPC 8 full level
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